



Product Change Notification / LIAL-07XYGF341

Date:

22-Mar-2021

Product Category:

Winpath Network Processors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3781.001 Final Notice: Qualification of an additional bill of material for T061NHEI and WP3061WxNHEI Microsemi device families available in 528L HBFPGA (19x19x2.71mm) package at ASE assembly site.

Affected CPNs:

[LIAL-07XYGF341_Affected_CPN_03222021.pdf](#)

[LIAL-07XYGF341_Affected_CPN_03222021.csv](#)

Notification Text:

PCN Status:Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of an additional bill of material for T061NHEI and WP3061WxNHEI Microsemi device families available in 528L HBFPGA (19x19x2.71mm) package at ASE assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	ASE Inc. (ASE)
Bump material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag

Die attach material	WS446	WS446	WS446
Underfill material	UH12	UH12	UH12
Substrate core material	E-679 FGR	E-679 FGR	E705G
SM Material	PSR 4000 AUS703-140Ps	PSR 4000 AUS703-140Ps	SR7300GR
Thermal Grease material	SE-4450	SE-4450	SE-4450
Solder ball material	SAC305	SAC305	SAC305
Solder Ball Flux	WF6400	WF6400	WF6400

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying an additional bill of material for T061NHEI and WP3061WxNHEI Microsemi device families available in 528L HBFPGA (19x19x2.71mm) package at ASE assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:April 15, 2021 (date code: 2116)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2021					April 2021				
Workweek	10	11	12	13	14	15	16	17	18	19
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated Implementation Date							X			

Method to Identify Change:Traceability code

Qualification ReportPlease open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:March 22, 2021: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on April 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-07XYGF341_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

T061NHEI-250B1

T061NHEI-320B1

WP3061W1NHEI-250B1

WP3061W2NHEI-250B1

WP3061W8NHEI-250B1